



# Micromegas module(s) + Silicon enveloppe

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Test performed from Nov. 3 to Nov. 6, 2009 at DESY.

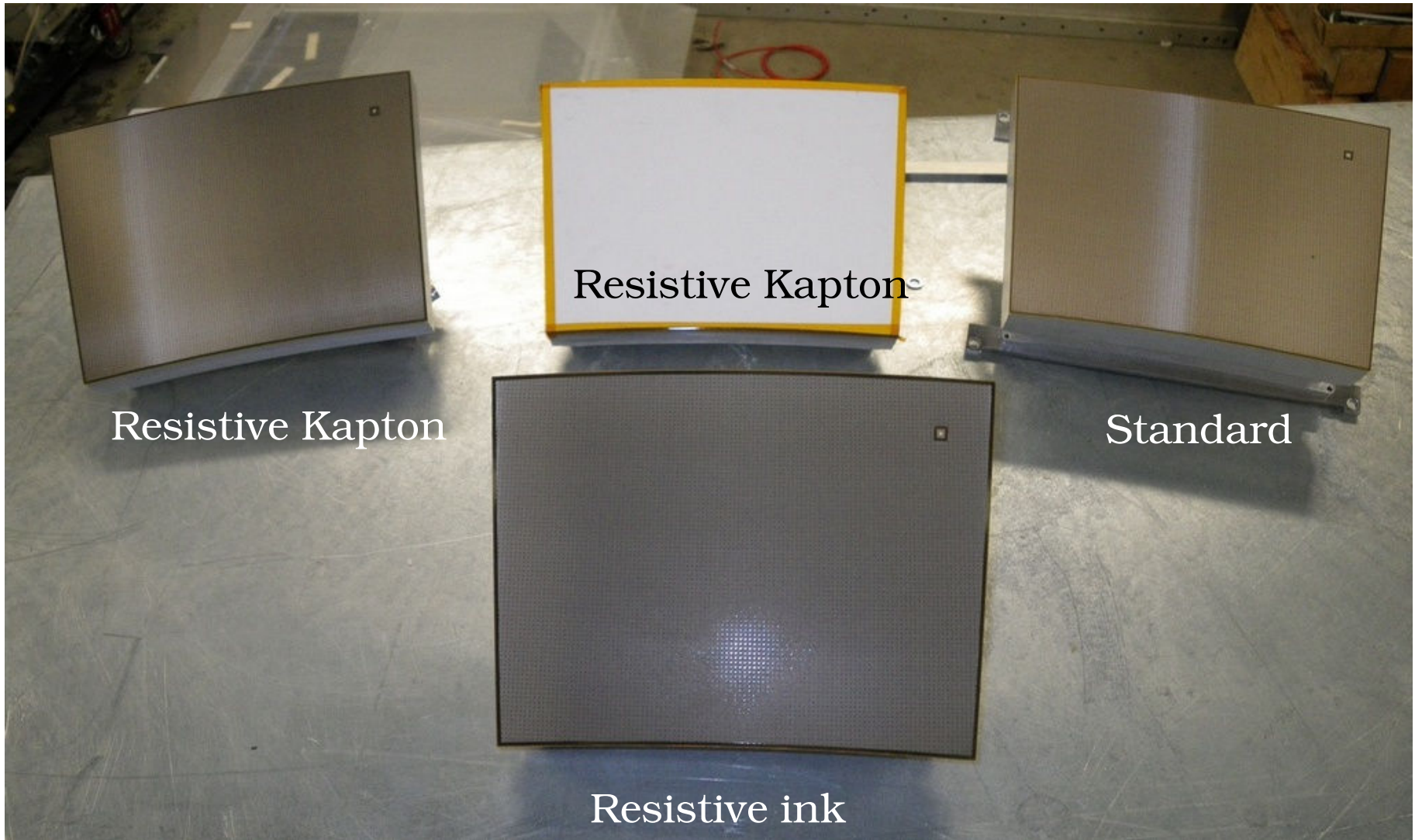
Phone WP meeting, Nov.11, 2009

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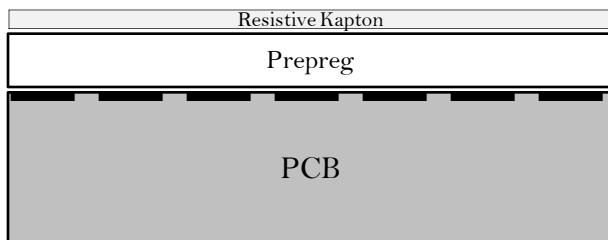


Carleton  
UNIVERSITY

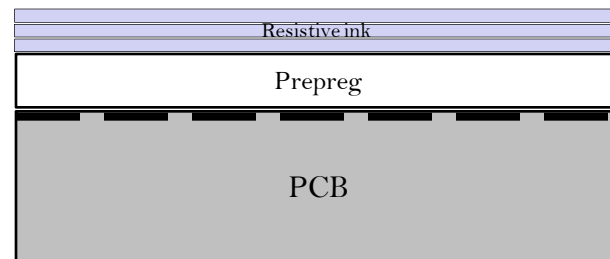




Resistive Kapton



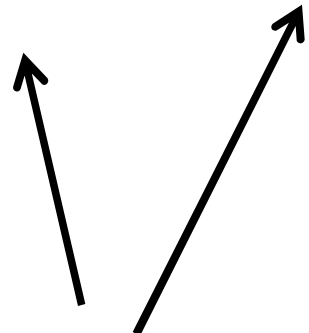
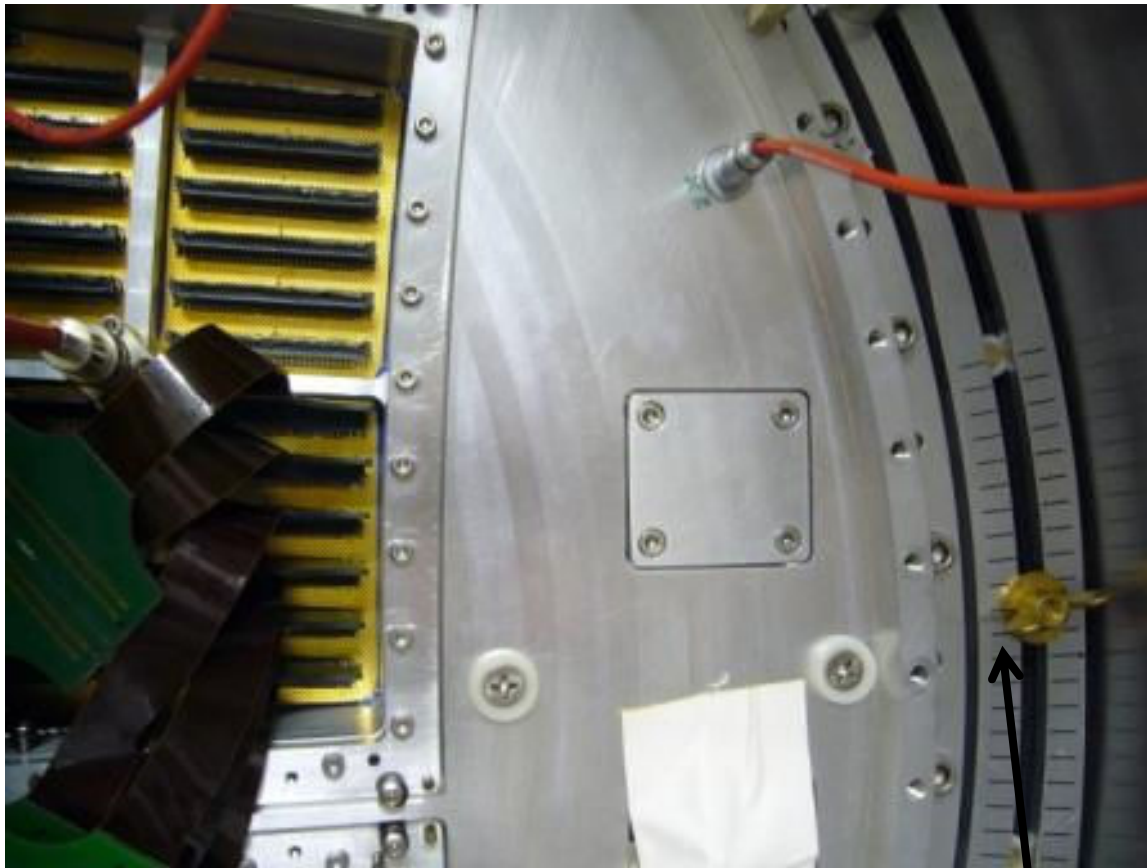
Resistive ink



New kapton adapted to 200 ns shaping time : close to optimum

Détecteur	Dielectric layer	Resistive layer	Resistivity (MΩ/□)
Resistive Kapton	Epoxy glass 75 μm	C-loaded Kapton 25 μm	~4-8 (now 2.8 times less)
Resistive Ink	Epoxy glass 75 μm	Ink (3 layers) ~50 μm	~1-2

Collage par lamination et chauffage (technique PCB)

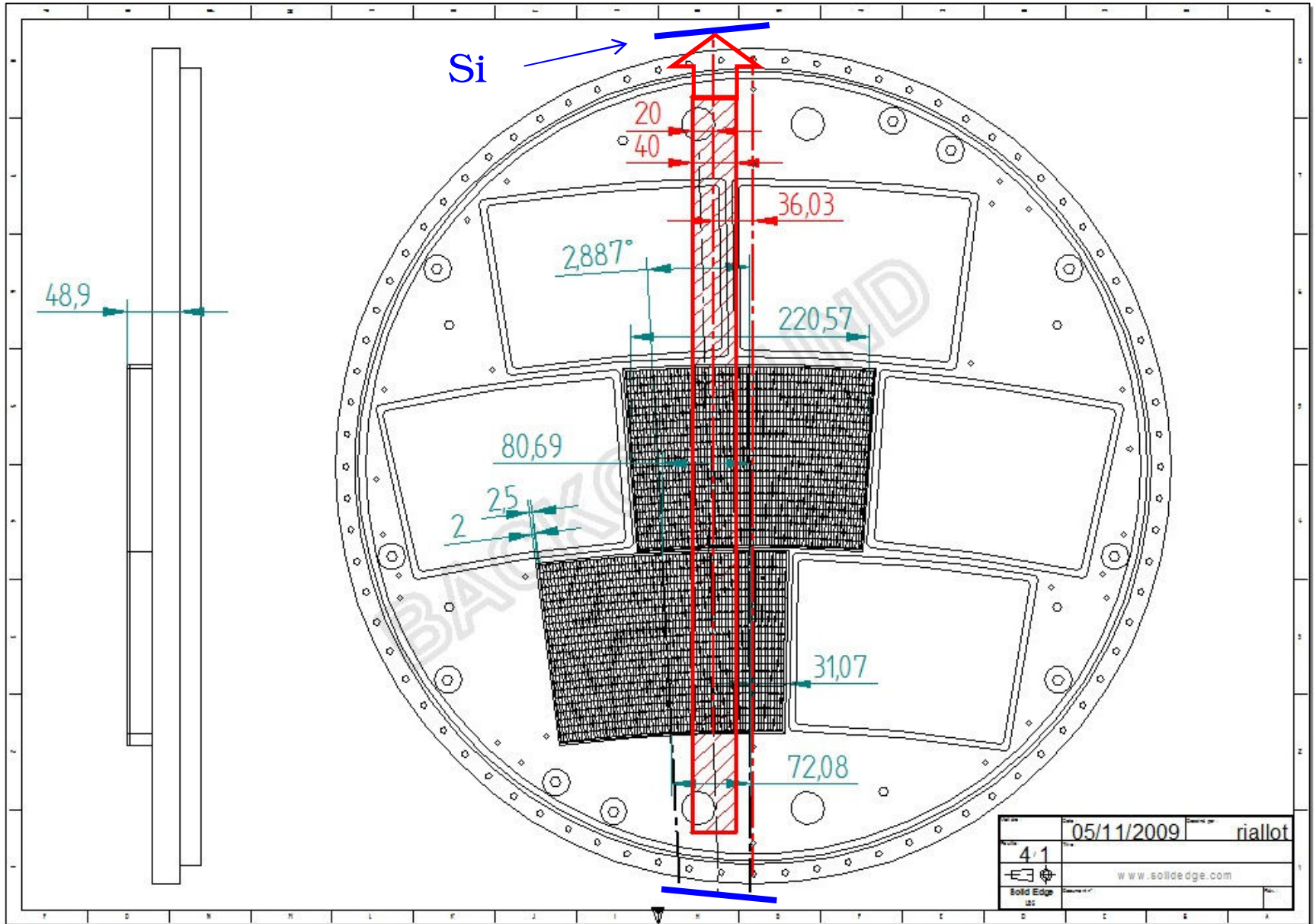


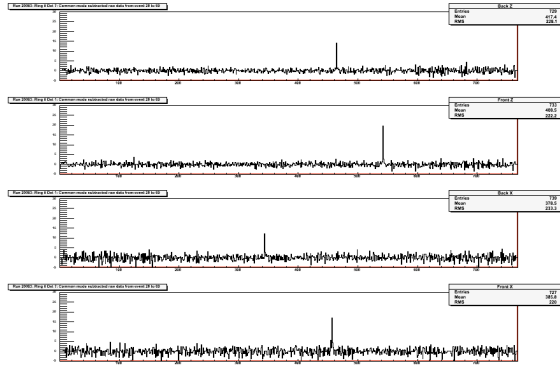
2 half Micromegas modules connected



Silicon module

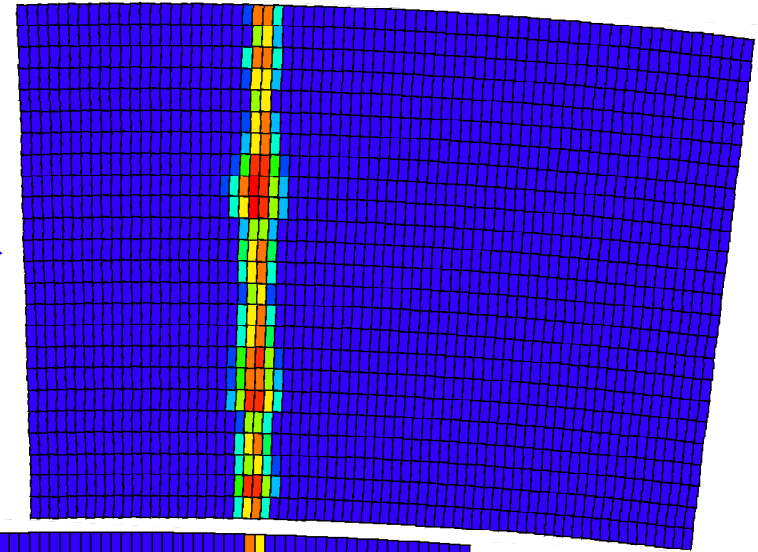




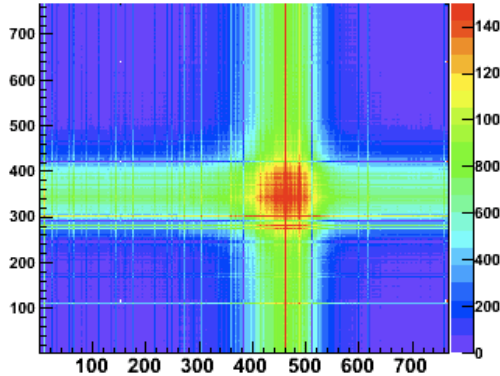


TLU

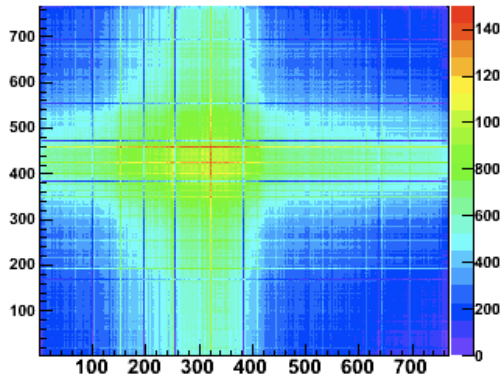
Resistive Ink



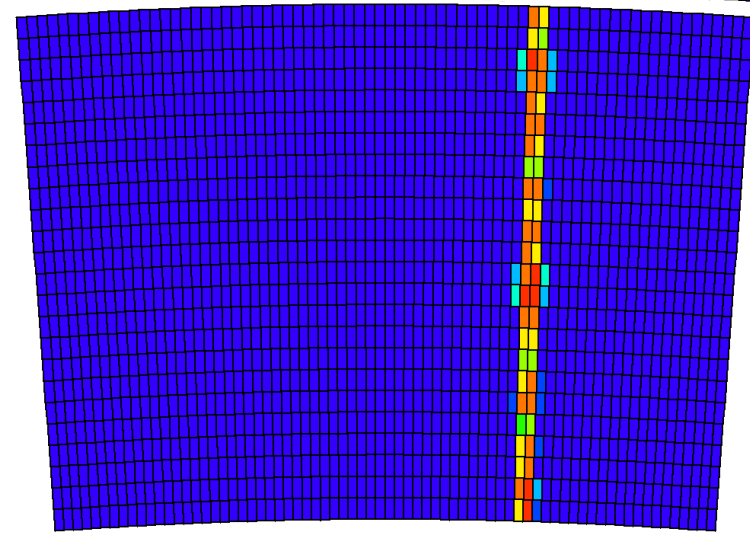
Front Modules



Back Modules



Resistive Kapton





- One Micromegas TPC module data
  - Run 805 11000 synchronized events
  - Run 808 19000 synchronized events
- Two Micromegas TPC modules
  - Runs 815 to 820 : 75000 synchronized events and 150000 TPC only events (disk problem in Si DAQ in the night).
- The two detectors performed very well and the TLU could be used to synchronize their (separate) DAQ's. Next step would be to take data with B-field, with an EUDAQ event builder.
- Information on <http://elog.hephy.at/LP-TPC>
- Plan to take some data with the new modules in December at  $B=0$ , and to take a final run with  $B=1T$  between 4th and 24th of March 2010.